IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Hiroshi HAJI et al.) Attn: APPLICATIONS BRANCH
Serial No.: To Be Assigned))
Filed: February 13, 2001))
For: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE)))

PRELIMINARY AMENDMENT

Hon. Assistant Commissioner for Patents Washington, DC 20231

Sir:

Prior to examination of the above-identified application, please amend the application as follows:

IN THE SPECIFICATION:

Please amend the specification as follows:

Page 1, line 6: after "device," insert --and--.

Page 2, line 9: after "right" insert --proper--.

Page 4, line 19: after "may be" insert --uniformly-- and delete "uniformly".

Page 5, line 2: change "the" (first occurrence) to --these--;

line 11: after "wafer 1" insert --to be--;

line 13: after "irradiating" insert --a--; and

lines 22/23: change "with giving no" to --without--.

Page 6, line 9: change "pieces," to --piece,--;

line 10: change "its" to --a--, and change "to be" to --which is--;

line 13: change "inconveniences" to --variations--, and "falling down" to

--moving--;

line 18: change "reaching" to --and coupled--.

Page 8, line 4: change "occurring" to --having--;

line 7: change "processed" to --processing--; and

line 17: change "reached" to --coupled--.

Page 9, line 3: change "stuck with" to --applied thereto via--.

Page 10, line 3: change "occurring" to --having--; and

line 17: after "manufacturing" insert --a--.

Page 11, line 3: delete "to" (second occurrence).

REMARKS

Prior to the examination of the instant application, Applicants have amended the specification to correct minor errors. No new matter has been added.

Respectfully submitted,

McDERMOTT, WILL & EMERY

Date: 2 /13/01

By:

Michael E. Fogarty/ Registration No. 36,139

600 13th Street, N.W., Suite 1200 Washington, D.C. 20005-3096 Telephone: 202-756-8000 Facsimile: 202-756-8087

. 400......

WDC99 389272-1.043890 0485